

## 描述 / Descriptions

SOT-23 塑封封装 硅 NPN 数字三极管。Silicon NPN Digital transistor in a SOT-23 Plastic Package.

## 特征 / Features

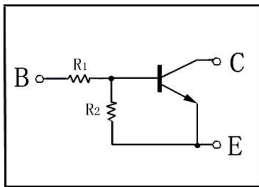
内装偏置电阻，简化线路设计，减少元件和制造流程，符合 AEC-Q101 标准高可靠性要求，无卤产品。  
With built-in bias resistors, simplify circuit design, reduce a quantity of parts and manufacturing process, Qualified to AEC-Q101 Standards for High Reliability, HF Product.

## 用途 / Applications

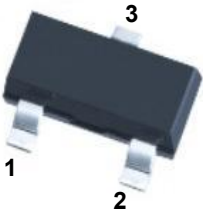
用于开关、界面电路以及驱动电路中，满足汽车应用的严格要求。

Switching applications, interface circuit and driver circuit applications, Meet the stringent requirements of automotive applications.

## 内部等效电路 / Equivalent Circuit



## 引脚排列 / Pinning



PIN 1 : Base

PIN 2 : Emitter

PIN 3 : Collector

## 放大及印章代码 / $h_{FE}$ Classifications & Marking

Marking	Q23
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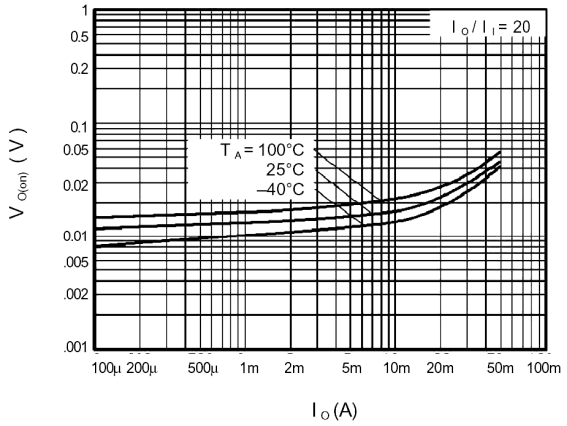
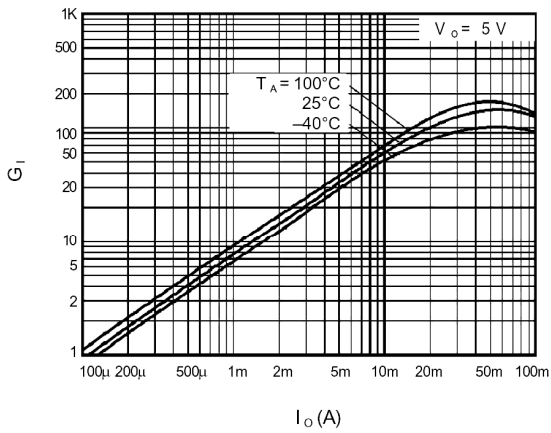
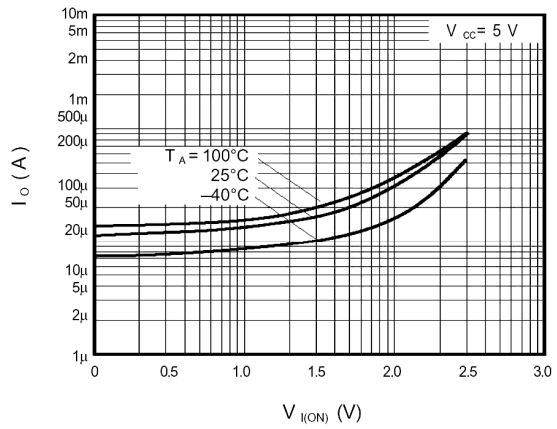
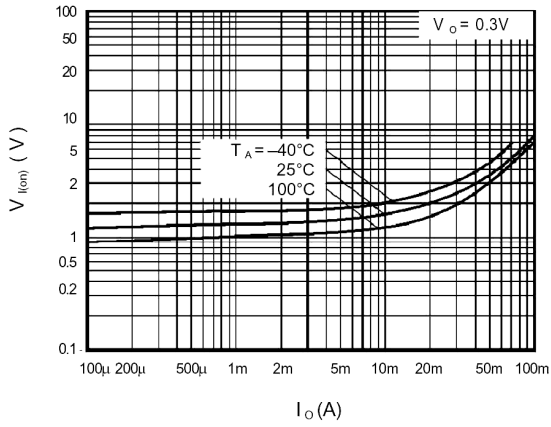
**极限参数 / Absolute Maximum Ratings(Ta=25°C)**

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Output Voltage	$V_{CC}$	50	V
Input Voltage	$V_{IN}$	30	V
		-10	V
Output Current	$I_{CM}$	100	mA
	$I_O$	100	mA
Power Dissipation	$P_C$	200	mW
Junction Temperature	$T_j$	150	°C
Storage Temperature Range	$T_{stg}$	-55~150	°C

**电性能参数 / Electrical Characteristics(Ta=25°C)**

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Input Voltage(OFF)	$V_{I(off)}$	$V_{CC}=5.0V$ $I_O=0.1mA$			0.5	V
Input Voltage(ON)	$V_{I(on)}$	$V_O=0.3V$ $I_O=20mA$	3.0			V
Output Voltage	$V_{O(on)}$	$I_O=10mA$ $I_I=0.5mA$		0.1	0.3	V
Input Current	$I_I$	$V_I=5.0V$			1.8	mA
Output Cut-off Current	$I_{O(off)}$	$V_{CC}=50V$ $V_I=0$			0.5	$\mu A$
DC Current Gain	$G_I$	$V_O=5.0V$ $I_O=10mA$	20			
Transition Frequency	$f_T$	$V_{CE}=10V$ $I_E=-5.0Ma$ $f=100MHz$		250		MHz
Resistance1	$R_1$		3.29	4.7	6.11	K $\Omega$
Resistance Ratio	$R_2/R_1$		0.8	1.0	1.2	

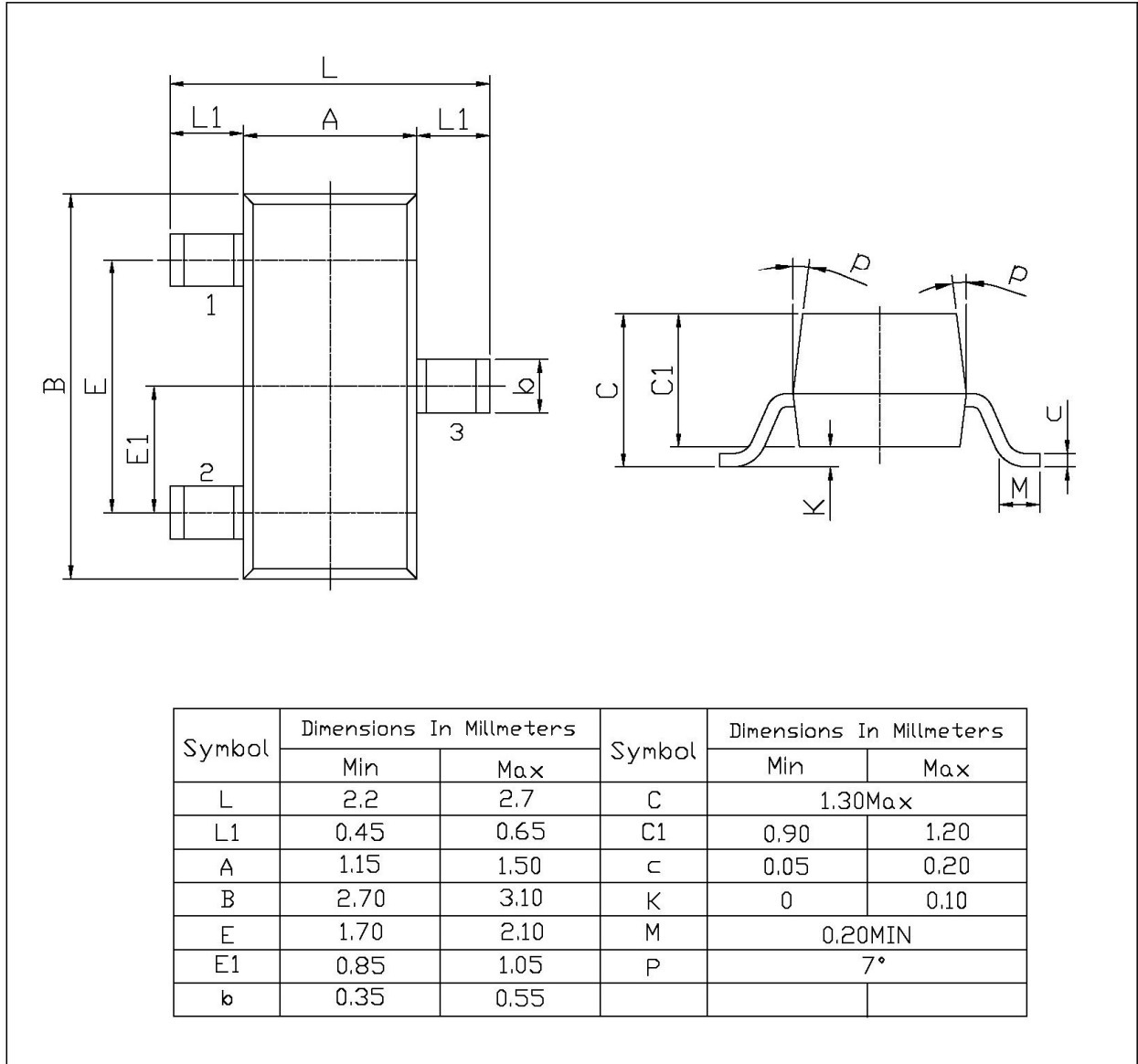
电参数曲线图 / Electrical Characteristic Curve



外形尺寸图 / Package Dimensions

SOT-23

单位: mm



印章说明 / Marking Instructions



说明：

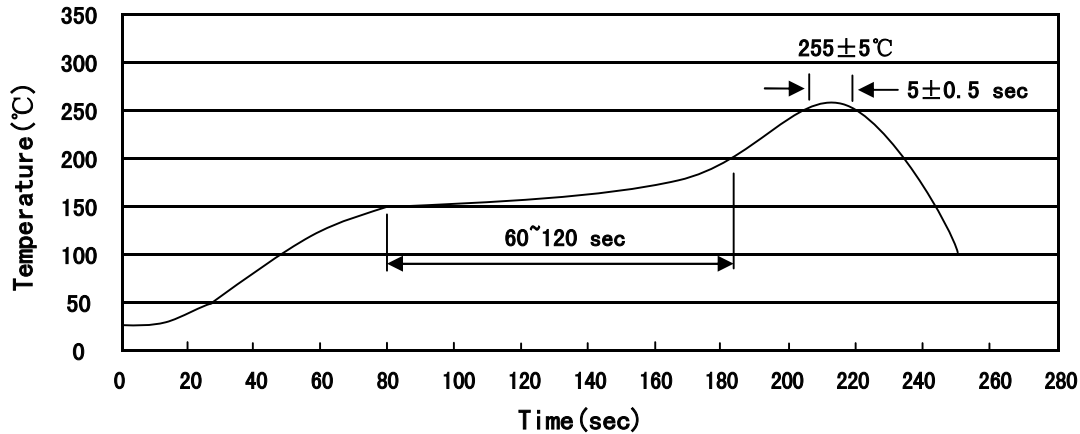
Q： 为汽车无卤产品标识

23： 为型号代码

Note:

Q: Automobile halogen-free product Code

23: Product Type

**回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)**


说明：

- 1、预热温度 150~200°C，时间 60~120sec;
- 2、峰值温度 255±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2~10°C/sec.

Note:

- 1.Preheating:150~200°C, Time:60~120sec.
- 2.Peak Temp.:255±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

**耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions**

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

**包装规格 / Packaging SPEC.**

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOT-23	3,000	10	30,000	6	180,000	7" ×8	180×120×180	390×385×205

**使用说明 / Notices**